

LINEAR TECHNOLOGY MATERIALS DECLARATION

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(Engineering Calculation)

SOIC WIDE

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TOTAL MASS (g) : 0.547262

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------------|----------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|----------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.008788 | 1000000 | 16058.1298828 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000000 | 0 | 0 | | |
| Lead Frame | Cu | Copper (Cu) | 7440-50-8 | 0.153163 | 975000 | 279871.59375 | | |
| | | Iron (Fe) | 7439-89-6 | 0.003770 | 24000 | 6888.84326172 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000047 | 300 | 85.8821258545 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000110 | 700 | 201.000732422 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| Lead Frame Total: | | | | 0.157090 | 1000000 | 287047.28125 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.005974 | 1000000 | 10915.5761719 | | |
| | | External Plating Total: | | | | 0.005974 | 1000000 | 10915.5761719 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.001257 | 1000000 | 2296.89013672 | | |
| Internal Plating Total: | | | | 0.001257 | 1000000 | 2296.89013672 | | |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.001955 | 750000 | 3572.33105469 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000652 | 250000 | 1191.3861084 | | |
| Die Attach Total: | | | | 0.002607 | 1000000 | 4763.71728516 | | |
| Encapsulation | MULTI-AROMATIC RESIN Br/Sb FREE | Resin (EP) | | 0.038213 | 103000 | 69825.8203125 | | |
| | | Bromine (Br) | 40039-93-8 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.332045 | 895000 | 606738.9375 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.000000 | 0 | 0 | | |
| | | Metal Hydroxide | | 0.000000 | 0 | 0 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.000742 | 2000 | 1355.84130859 | | |
| | | Encapsulation Total: | | | | 0.371000 | 1000000 | 677920.5625 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.000546 | 1000000 | 997.694580078 | | |
| | | | | | TOTAL MASS (g) : | 0.547262 | | |